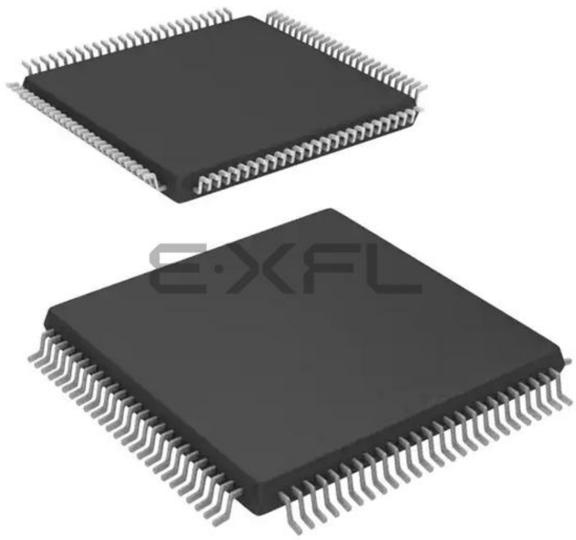
Silicon Labs - EFM32GG11B520F2048GQ100-B Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	72MHz
Connectivity	CANbus, EBI/EMI, I²C, IrDA, LINbus, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	83
Program Memory Size	2MB (2M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.8V
Data Converters	A/D 16x12b SAR; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32gg11b520f2048gq100-b

1. Feature List

The EFM32GG11 highlighted features are listed below.

- **ARM Cortex-M4 CPU platform**
  - High performance 32-bit processor @ up to 72 MHz
  - DSP instruction support and Floating Point Unit
  - Memory Protection Unit
  - Wake-up Interrupt Controller
- **Flexible Energy Management System**
  - 80 µA/MHz in Active Mode (EM0)
  - 2.1 µA EM2 Deep Sleep current (16 kB RAM retention and RTCC running from LFRCO)
- **Integrated DC-DC buck converter**
- **Up to 2048 kB flash program memory**
  - Dual-bank with read-while-write support
- **Up to 512 kB RAM data memory**
  - 256 kB with ECC (SEC-DED)
- **Octal/Quad-SPI Flash Memory Interface**
  - Supports 3 V and 1.8 V memories
  - 1/2/4/8-bit data bus
  - Quad-SPI Execute In Place (XIP)
- **Communication Interfaces**
  - Low-energy Universal Serial Bus (USB) with Device and Host support
    - Fully USB 2.0 compliant
    - On-chip PHY and embedded 5V to 3.3V regulator
    - Crystal-free Device mode operation
    - Patent-pending Low-Energy Mode (LEM)
  - SD/MMC/SDIO Host Controller
    - SD v3.01, SDIO v3.0 and MMC v4.51
    - 1/4/8-bit bus width
  - 10/100 Ethernet MAC with MII/RMII interface
    - IEEE1588-2008 precision time stamping
    - Energy Efficient Ethernet (802.3az)
  - Up to 2× CAN Bus Controller
    - Version 2.0A and 2.0B up to 1 Mbps
  - 6× Universal Synchronous/Asynchronous Receiver/ Transmitter
    - UART/SPI/SmartCard (ISO 7816)/IrDA/I2S/LIN
    - Triple buffered full/half-duplex operation with flow control
    - Ultra high speed (36 MHz) operation on one instance
  - 2× Universal Asynchronous Receiver/ Transmitter
  - 2× Low Energy UART
    - Autonomous operation with DMA in Deep Sleep Mode
  - 3× I^2C Interface with SMBus support
    - Address recognition in EM3 Stop Mode
- **Up to 144 General Purpose I/O Pins**
  - Configurable push-pull, open-drain, pull-up/down, input filter, drive strength
  - Configurable peripheral I/O locations
  - 5 V tolerance on select pins
  - Asynchronous external interrupts
  - Output state retention and wake-up from Shutoff Mode
- **Up to 24 Channel DMA Controller**
- **Up to 24 Channel Peripheral Reflex System (PRS) for autonomous inter-peripheral signaling**
- **External Bus Interface for up to 4x256 MB of external memory mapped space**
  - TFT Controller with Direct Drive
  - Per-pixel alpha-blending engine
- **Hardware Cryptography**
  - AES 128/256-bit keys
  - ECC B/K163, B/K233, P192, P224, P256
  - SHA-1 and SHA-2 (SHA-224 and SHA-256)
  - True Random Number Generator (TRNG)
- **Hardware CRC engine**
  - Single-cycle computation with 8/16/32-bit data and 16-bit (programmable)/32-bit (fixed) polynomial
- **Security Management Unit (SMU)**
  - Fine-grained access control for on-chip peripherals
- **Integrated Low-energy LCD Controller with up to 8×36 segments**
  - Voltage boost, contrast and autonomous animation
  - Patented low-energy LCD driver
- **Backup Power Domain**
  - RTCC and retention registers in a separate power domain, available down to energy mode EM4H
  - Operation from backup battery when main power absent/ insufficient
- **Ultra Low-Power Precision Analog Peripherals**
  - 2× 12-bit 1 Msamples/s Analog to Digital Converter (ADC)
    - On-chip temperature sensor
  - 2× 12-bit 500 ksamples/s Digital to Analog Converter (VDAC)
  - Digital to Analog Current Converter (IDAC)
  - Up to 4× Analog Comparator (ACMP)
  - Up to 4× Operational Amplifier (OPAMP)
  - Robust current-based capacitive sensing with up to 64 inputs and wake-on-touch (CSEN)
  - Up to 108 GPIO pins are analog-capable. Flexible analog peripheral-to-pin routing via Analog Port (APORT)
  - Supply Voltage Monitor

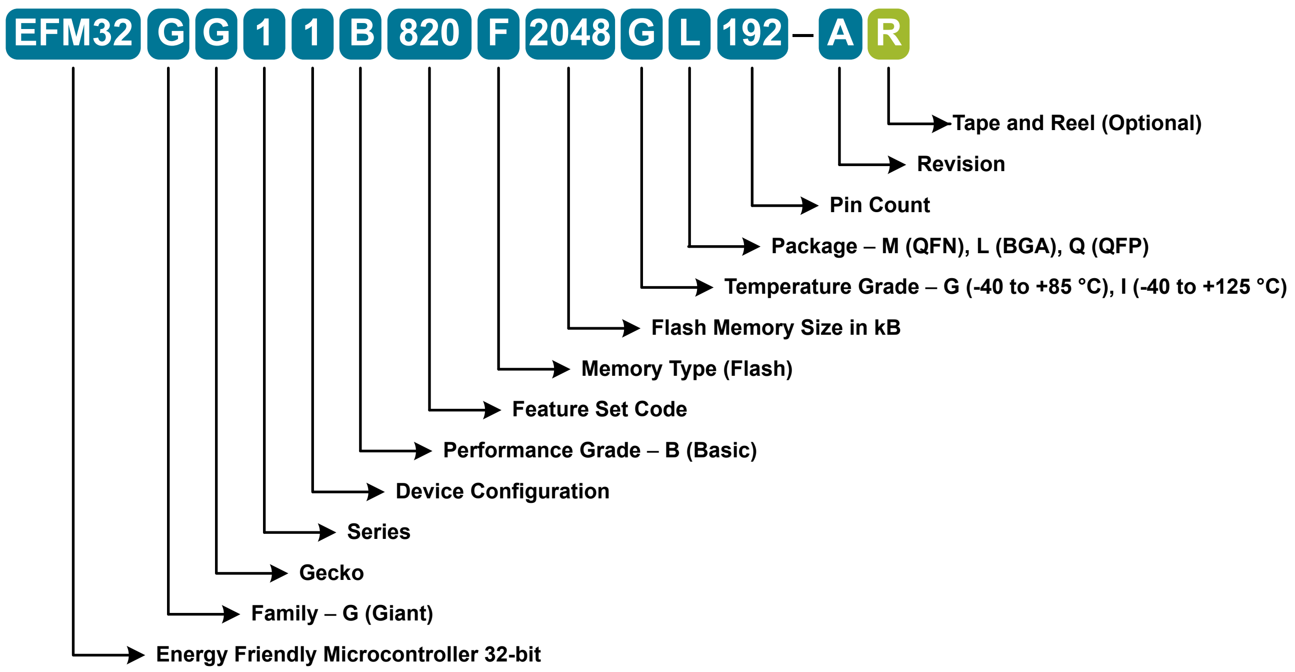

Figure 2.1. Ordering Code Key

3.4.2 Internal and External Oscillators

The EFM32GG11 supports two crystal oscillators and fully integrates five RC oscillators, listed below.

- A high frequency crystal oscillator (HFXO) with integrated load capacitors, tunable in small steps, provides a precise timing reference for the MCU. Crystal frequencies in the range from 4 to 50 MHz are supported. An external clock source such as a TCXO can also be applied to the HFXO input for improved accuracy over temperature.
- A 32.768 kHz crystal oscillator (LFXO) provides an accurate timing reference for low energy modes.
- An integrated high frequency RC oscillator (HFRCO) is available for the MCU system. The HFRCO employs fast startup at minimal energy consumption combined with a wide frequency range. When crystal accuracy is not required, it can be operated in free-running mode at a number of factory-calibrated frequencies. A digital phase-locked loop (DPLL) feature allows the HFRCO to achieve higher accuracy and stability by referencing other available clock sources such as LFXO and HFXO.
- An integrated auxilliary high frequency RC oscillator (AUXHFRCO) is available for timing the general-purpose ADC and the Serial Wire Viewer port with a wide frequency range.
- An integrated auxilliary high frequency RC oscillator (USHFRCO) is available for timing the USB, SDIO and QSPI peripherals. The USHFRCO can be syncronized to the host's USB clock to allow the USB to operate in device mode without the additional cost of an external crystal.
- An integrated low frequency 32.768 kHz RC oscillator (LFRCO) can be used as a timing reference in low energy modes, when crystal accuracy is not required.
- An integrated ultra-low frequency 1 kHz RC oscillator (ULFRCO) is available to provide a timing reference at the lowest energy consumption in low energy modes.

3.5 Counters/Timers and PWM

3.5.1 Timer/Counter (TIMER)

TIMER peripherals keep track of timing, count events, generate PWM outputs and trigger timed actions in other peripherals through the PRS system. The core of each TIMER is a 16-bit counter with up to 4 compare/capture channels. Each channel is configurable in one of three modes. In capture mode, the counter state is stored in a buffer at a selected input event. In compare mode, the channel output reflects the comparison of the counter to a programmed threshold value. In PWM mode, the TIMER supports generation of pulse-width modulation (PWM) outputs of arbitrary waveforms defined by the sequence of values written to the compare registers, with optional dead-time insertion available in timer unit TIMER_0 only.

3.5.2 Wide Timer/Counter (WTIMER)

WTIMER peripherals function just as TIMER peripherals, but are 32 bits wide. They keep track of timing, count events, generate PWM outputs and trigger timed actions in other peripherals through the PRS system. The core of each WTIMER is a 32-bit counter with up to 4 compare/capture channels. Each channel is configurable in one of three modes. In capture mode, the counter state is stored in a buffer at a selected input event. In compare mode, the channel output reflects the comparison of the counter to a programmed threshold value. In PWM mode, the WTIMER supports generation of pulse-width modulation (PWM) outputs of arbitrary waveforms defined by the sequence of values written to the compare registers, with optional dead-time insertion available in timer unit WTIMER_0 only.

3.5.3 Real Time Counter and Calendar (RTCC)

The Real Time Counter and Calendar (RTCC) is a 32-bit counter providing timekeeping in all energy modes. The RTCC includes a Binary Coded Decimal (BCD) calendar mode for easy time and date keeping. The RTCC can be clocked by any of the on-board oscillators with the exception of the AUXHFRCO, and it is capable of providing system wake-up at user defined instances. The RTCC includes 128 bytes of general purpose data retention, allowing easy and convenient data storage in all energy modes down to EM4H.

3.5.4 Low Energy Timer (LETIMER)

The unique LETIMER is a 16-bit timer that is available in energy mode EM2 Deep Sleep in addition to EM1 Sleep and EM0 Active. This allows it to be used for timing and output generation when most of the device is powered down, allowing simple tasks to be performed while the power consumption of the system is kept at an absolute minimum. The LETIMER can be used to output a variety of waveforms with minimal software intervention. The LETIMER is connected to the Real Time Counter and Calendar (RTCC), and can be configured to start counting on compare matches from the RTCC.

3.5.5 Ultra Low Power Wake-up Timer (CRYOTIMER)

The CRYOTIMER is a 32-bit counter that is capable of running in all energy modes. It can be clocked by either the 32.768 kHz crystal oscillator (LFXO), the 32.768 kHz RC oscillator (LFRCO), or the 1 kHz RC oscillator (ULFRCO). It can provide periodic Wakeup events and PRS signals which can be used to wake up peripherals from any energy mode. The CRYOTIMER provides a wide range of interrupt periods, facilitating flexible ultra-low energy operation.

4. Electrical Specifications

4.1 Electrical Characteristics

All electrical parameters in all tables are specified under the following conditions, unless stated otherwise:

- Typical values are based on T_{AMB}=25 °C and V_{DD}= 3.3 V, by production test and/or technology characterization.
- Minimum and maximum values represent the worst conditions across supply voltage, process variation, and operating temperature, unless stated otherwise.

Refer to 4.1.2.1 General Operating Conditions for more details about operational supply and temperature limits.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Current consumption in EM2 mode, with voltage scaling enabled	I_{EM2_VS}	Full 512 kB RAM retention and RTCC running from LFXO	—	3.9	—	μA
		Full 512 kB RAM retention and RTCC running from LFRCO	—	4.3	—	μA
		16 kB (1 bank) RAM retention and RTCC running from LFRCO[2]	—	2.8	TBD	μA
Current consumption in EM3 mode, with voltage scaling enabled	I_{EM3_VS}	Full 512 kB RAM retention and CRYOTIMER running from ULFR-CO	—	3.6	TBD	μA
Current consumption in EM4H mode, with voltage scaling enabled	I_{EM4H_VS}	128 byte RAM retention, RTCC running from LFXO	—	1.08	—	μA
		128 byte RAM retention, CRYO-TIMER running from ULFRCO	—	0.69	—	μA
		128 byte RAM retention, no RTCC	—	0.69	TBD	μA
Current consumption in EM4S mode	I_{EM4S}	No RAM retention, no RTCC	—	0.16	TBD	μA
Current consumption of peripheral power domain 1, with voltage scaling enabled	I_{PD1_VS}	Additional current consumption in EM2/3 when any peripherals on power domain 1 are enabled[1]	—	0.68	—	μA
Current consumption of peripheral power domain 2, with voltage scaling enabled	I_{PD2_VS}	Additional current consumption in EM2/3 when any peripherals on power domain 2 are enabled[1]	—	0.28	—	μA

Note:

1. Extra current consumed by power domain. Does not include current associated with the enabled peripherals. See 3.2.4 EM2 and EM3 Power Domains for a list of the peripherals in each power domain.
2. CMU_LFRCOCTRL_ENVREF = 1, CMU_LFRCOCTRL_VREFUPDATE = 1

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Current consumption in EM4H mode, with voltage scaling enabled	I_{EM4H_VS}	128 byte RAM retention, RTCC running from LFXO	—	0.94	—	μA
		128 byte RAM retention, CRYO-TIMER running from ULFRCO	—	0.62	—	μA
		128 byte RAM retention, no RTCC	—	0.62	—	μA
Current consumption in EM4S mode	I_{EM4S}	No RAM retention, no RTCC	—	0.13	—	μA
Current consumption of peripheral power domain 1, with voltage scaling enabled, DCDC in LP mode[3]	I_{PD1_VS}	Additional current consumption in EM2/3 when any peripherals on power domain 1 are enabled[4]	—	0.68	—	μA
Current consumption of peripheral power domain 2, with voltage scaling enabled, DCDC in LP mode[3]	I_{PD2_VS}	Additional current consumption in EM2/3 when any peripherals on power domain 2 are enabled[4]	—	0.28	—	μA

Note:

1. DCDC Low Noise CCM Mode = Light Drive (PFETCNT=NFETCNT=3), F=6.4 MHz (RCOBAND=4), ANASW=DVDD.
2. DCDC Low Noise DCM Mode = Light Drive (PFETCNT=NFETCNT=3), F=3.0 MHz (RCOBAND=0), ANASW=DVDD.
3. DCDC Low Power Mode = Medium Drive (PFETCNT=NFETCNT=7), LPOSCDIV=1, LPCMPBIASEM234H=0, LPCLIMILIMSEL=1, ANASW=DVDD.
4. Extra current consumed by power domain. Does not include current associated with the enabled peripherals. See 3.2.4 EM2 and EM3 Power Domains for a list of the peripherals in each power domain.
5. CMU_LFRCOCTRL_ENVREF = 1, CMU_LFRCOCTRL_VREFUPDATE = 1

4.1.14 Analog to Digital Converter (ADC)

Specified at 1 Msps, ADCCLK = 16 MHz, BIASPROG = 0, GPBIASACC = 0, unless otherwise indicated.

Table 4.22. Analog to Digital Converter (ADC)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Resolution	$V_{RESOLUTION}$		6	—	12	Bits
Input voltage range[5]	V_{ADCIN}	Single ended	—	—	V_{FS}	V
		Differential	$-V_{FS}/2$	—	$V_{FS}/2$	V
Input range of external reference voltage, single ended and differential	$V_{ADCREFIN\_P}$		1	—	V_{AVDD}	V
Power supply rejection[2]	$PSRR_{ADC}$	At DC	—	80	—	dB
Analog input common mode rejection ratio	$CMRR_{ADC}$	At DC	—	80	—	dB
Current from all supplies, using internal reference buffer. Continous operation. WARMUPMODE[4] = KEEPADCWARM	$I_{ADC\_CONTINOUS\_LP}$	1 Msps / 16 MHz ADCCLK, BIASPROG = 0, GPBIASACC = 1 [3]	—	270	TBD	μA
		250 ksps / 4 MHz ADCCLK, BIASPROG = 6, GPBIASACC = 1 [3]	—	125	—	μA
		62.5 ksps / 1 MHz ADCCLK, BIASPROG = 15, GPBIASACC = 1 [3]	—	80	—	μA
Current from all supplies, using internal reference buffer. Duty-cycled operation. WARMUPMODE[4] = NORMAL	$I_{ADC\_NORMAL\_LP}$	35 ksps / 16 MHz ADCCLK, BIASPROG = 0, GPBIASACC = 1 [3]	—	45	—	μA
		5 ksps / 16 MHz ADCCLK BIASPROG = 0, GPBIASACC = 1 [3]	—	8	—	μA
Current from all supplies, using internal reference buffer. Duty-cycled operation. AWARMUPMODE[4] = KEEPINSTANDBY or KEEPINSLOWACC	$I_{ADC\_STANDBY\_LP}$	125 ksps / 16 MHz ADCCLK, BIASPROG = 0, GPBIASACC = 1 [3]	—	105	—	μA
		35 ksps / 16 MHz ADCCLK, BIASPROG = 0, GPBIASACC = 1 [3]	—	70	—	μA
Current from all supplies, using internal reference buffer. Continous operation. WARMUPMODE[4] = KEEPADCWARM	$I_{ADC\_CONTINOUS\_HP}$	1 Msps / 16 MHz ADCCLK, BIASPROG = 0, GPBIASACC = 0 [3]	—	325	—	μA
		250 ksps / 4 MHz ADCCLK, BIASPROG = 6, GPBIASACC = 0 [3]	—	175	—	μA
		62.5 ksps / 1 MHz ADCCLK, BIASPROG = 15, GPBIASACC = 0 [3]	—	125	—	μA
Current from all supplies, using internal reference buffer. Duty-cycled operation. WARMUPMODE[4] = NORMAL	$I_{ADC\_NORMAL\_HP}$	35 ksps / 16 MHz ADCCLK, BIASPROG = 0, GPBIASACC = 0 [3]	—	85	—	μA
		5 ksps / 16 MHz ADCCLK BIASPROG = 0, GPBIASACC = 0 [3]	—	16	—	μA
Current from all supplies, using internal reference buffer. Duty-cycled operation. AWARMUPMODE[4] = KEEPINSTANDBY or KEEPINSLOWACC	$I_{ADC\_STANDBY\_HP}$	125 ksps / 16 MHz ADCCLK, BIASPROG = 0, GPBIASACC = 0 [3]	—	160	—	μA
		35 ksps / 16 MHz ADCCLK, BIASPROG = 0, GPBIASACC = 0 [3]	—	125	—	μA
Current from HFPERCLK	I_{ADC_CLK}	HFPERCLK = 16 MHz	—	180	—	μA

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Start up time	t_{IDAC_SU}	Output within 1% of steady state value	—	5	—	µs
Settling time, (output settled within 1% of steady state value),	t_{IDAC_SETTLE}	Range setting is changed	—	5	—	µs
		Step value is changed	—	1	—	µs
Current consumption[2]	I_{IDAC}	EM0 or EM1 Source mode, excluding output current, Across operating temperature range	—	11	TBD	µA
		EM0 or EM1 Sink mode, excluding output current, Across operating temperature range	—	13	TBD	µA
		EM2 or EM3 Source mode, excluding output current, T = 25 °C	—	0.05	—	µA
		EM2 or EM3 Sink mode, excluding output current, T = 25 °C	—	0.07	—	µA
		EM2 or EM3 Source mode, excluding output current, T ≥ 85 °C	—	11	—	µA
		EM2 or EM3 Sink mode, excluding output current, T ≥ 85 °C	—	13	—	µA
Output voltage compliance in source mode, source current change relative to current sourced at 0 V	I_{COMP_SRC}	RANGESEL1=0, output voltage = min(V_{IOVDD}, V_{AVDD}[2]-100 mv)	—	0.11	—	%
		RANGESEL1=1, output voltage = min(V_{IOVDD}, V_{AVDD}[2]-100 mV)	—	0.06	—	%
		RANGESEL1=2, output voltage = min(V_{IOVDD}, V_{AVDD}[2]-150 mV)	—	0.04	—	%
		RANGESEL1=3, output voltage = min(V_{IOVDD}, V_{AVDD}[2]-250 mV)	—	0.03	—	%
Output voltage compliance in sink mode, sink current change relative to current sunk at IOVDD	I_{COMP_SINK}	RANGESEL1=0, output voltage = 100 mV	—	0.29	—	%
		RANGESEL1=1, output voltage = 100 mV	—	0.27	—	%
		RANGESEL1=2, output voltage = 150 mV	—	0.12	—	%
		RANGESEL1=3, output voltage = 250 mV	—	0.03	—	%

Note:

1. In IDAC_CURPROG register.
2. The IDAC is supplied by either AVDD, DVDD, or IOVDD based on the setting of ANASW in the EMU_PWRCTRL register and PWRSEL in the IDAC_CTRL register. Setting PWRSEL to 1 selects IOVDD. With PWRSEL cleared to 0, ANASW selects between AVDD (0) and DVDD (1).

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Slew rate[5]	SR	DRIVESTRENGTH = 3, INCBW=1[3]	—	4.7	—	V/μs
		DRIVESTRENGTH = 3, INCBW=0	—	1.5	—	V/μs
		DRIVESTRENGTH = 2, INCBW=1[3]	—	1.27	—	V/μs
		DRIVESTRENGTH = 2, INCBW=0	—	0.42	—	V/μs
		DRIVESTRENGTH = 1, INCBW=1[3]	—	0.17	—	V/μs
		DRIVESTRENGTH = 1, INCBW=0	—	0.058	—	V/μs
		DRIVESTRENGTH = 0, INCBW=1[3]	—	0.044	—	V/μs
		DRIVESTRENGTH = 0, INCBW=0	—	0.015	—	V/μs
Startup time[6]	T_{START}	DRIVESTRENGTH = 2	—	—	12	μs
Input offset voltage	V_{OSI}	DRIVESTRENGTH = 2 or 3, T = 25 °C	TBD	—	TBD	mV
		DRIVESTRENGTH = 1 or 0, T = 25 °C	TBD	—	TBD	mV
		DRIVESTRENGTH = 2 or 3, across operating temperature range	TBD	—	TBD	mV
		DRIVESTRENGTH = 1 or 0, across operating temperature range	TBD	—	TBD	mV
DC power supply rejection ratio[9]	$PSRR_{DC}$	Input referred	—	70	—	dB
DC common-mode rejection ratio[9]	$CMRR_{DC}$	Input referred	—	70	—	dB
Total harmonic distortion	THD_{OPA}	DRIVESTRENGTH = 2, 3x Gain connection, 1 kHz, V_{OUT} = 0.1 V to V_{OPA} - 0.1 V	—	90	—	dB
		DRIVESTRENGTH = 0, 3x Gain connection, 0.1 kHz, V_{OUT} = 0.1 V to V_{OPA} - 0.1 V	—	90	—	dB

EBI Read Enable Output Timing

Timing applies to both EBI_REn and EBI_NANDREn for all addressing modes and both polarities. Output timing for EBI_AD applies only to multiplexed addressing modes D8A24ALE and D16A16ALE. All numbers are based on route locations 0,1,2 only (with all EBI alternate functions using the same location at the same time). Timing is specified at 10% and 90% of IOVDD, 25 pF external loading, and slew rate for all GPIO set to 6.

Table 4.38. EBI Read Enable Output Timing

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Output hold time, from trailing EBI_REn / EBI_NANDREn edge to EBI_AD, EBI_A, EBI_CSn, EBI_BLn invalid	t_{OH_REn}	IOVDD ≥ 1.62 V	-23 + (RDHOLD * $t_{HFCORECLK}$)	—	—	ns
		IOVDD ≥ 3.0 V	-13 + (RDHOLD * $t_{HFCORECLK}$)	—	—	ns
Output setup time, from EBI_AD, EBI_A, EBI_CSn, EBI_BLn valid to leading EBI_REn / EBI_NANDREn edge [1]	t_{OSU_REn}	IOVDD ≥ 1.62 V	-12 + (RDSETUP * $t_{HFCORECLK}$)	—	—	ns
		IOVDD ≥ 3.0 V	-11 + (RDSETUP * $t_{HFCORECLK}$)	—	—	ns
EBI_REn pulse width [1] [2]	t_{WIDTH_REn}	IOVDD ≥ 1.62 V	-6 + (MAX(1, RDSTRB) * $t_{HFCORECLK}$)	—	—	ns
		IOVDD ≥ 3.0 V	-4 + (MAX(1, RDSTRB) * $t_{HFCORECLK}$)	—	—	ns

Note:

1. The figure shows the timing for the case that the half strobe length functionality is not used, i.e. HALFRE=0. The leading edge of EBI_REn can be moved to the right by setting HALFRE=1. This decreases the length of t_{WIDTH_REn} and increases the length of t_{OSU_REn} by 1/2 * $t_{HFCLKNODIV}$.
2. When page mode is used, RDSTRB is replaced by RDPA for page hits.

4.1.26 Ethernet (ETH)

MII Transmit Timing

Timing is specified with 3.0 V ≤ IOVDD ≤ 3.8 V, 25 pF external loading, and slew rate for all GPIO set to 6 unless otherwise indicated.

Table 4.42. Ethernet MII Transmit Timing

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
TX_CLK frequency	F_{TX_CLK}	Output slew rate set to 7	—	25	—	MHz
TX_CLK duty cycle	DC_{TX_CLK}		35	—	65	%
Output delay, TX_CLK to TXD[3:0], TX_EN, TX_ER	t_{OUT}		0	—	25	ns

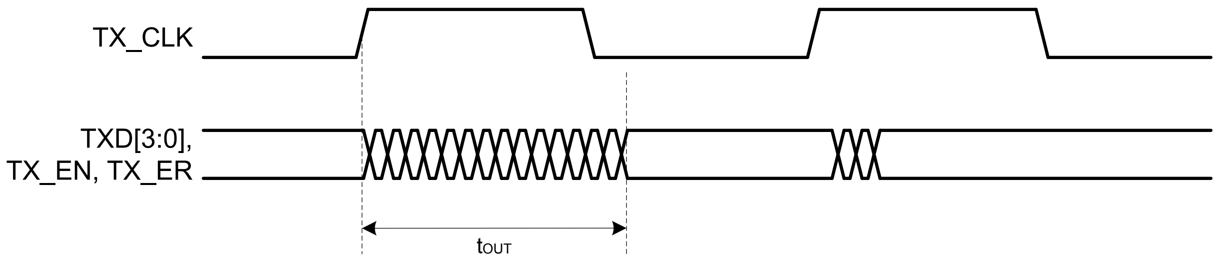

Figure 4.9. Ethernet MII Transmit Timing

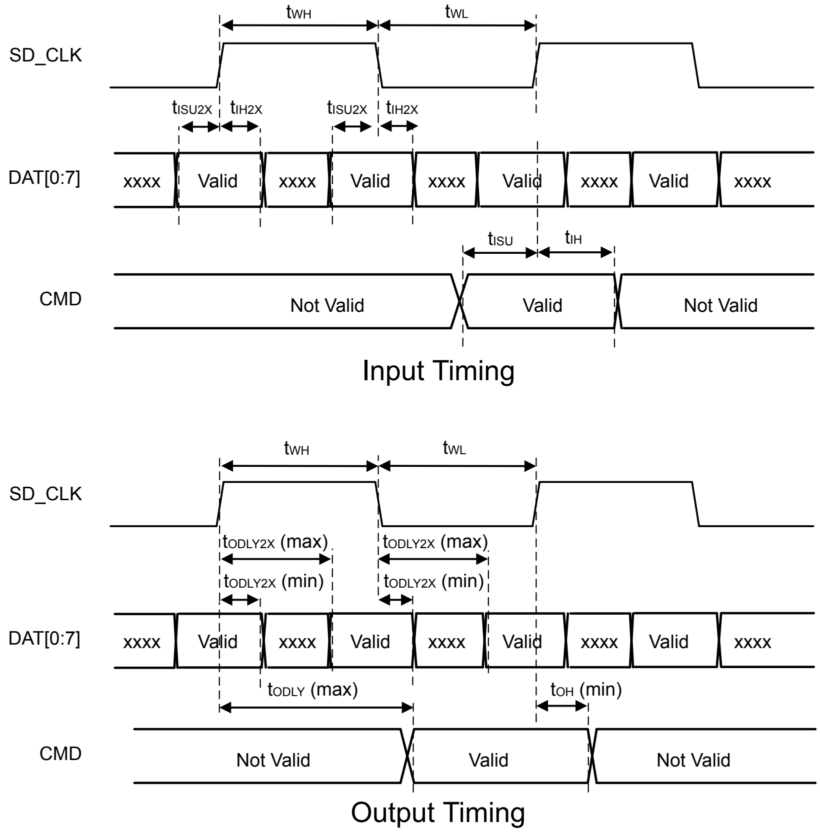

Figure 4.19. SDIO MMC DDR Mode Timing

5.3 EFM32GG11B8xx in BGA120 Device Pinout

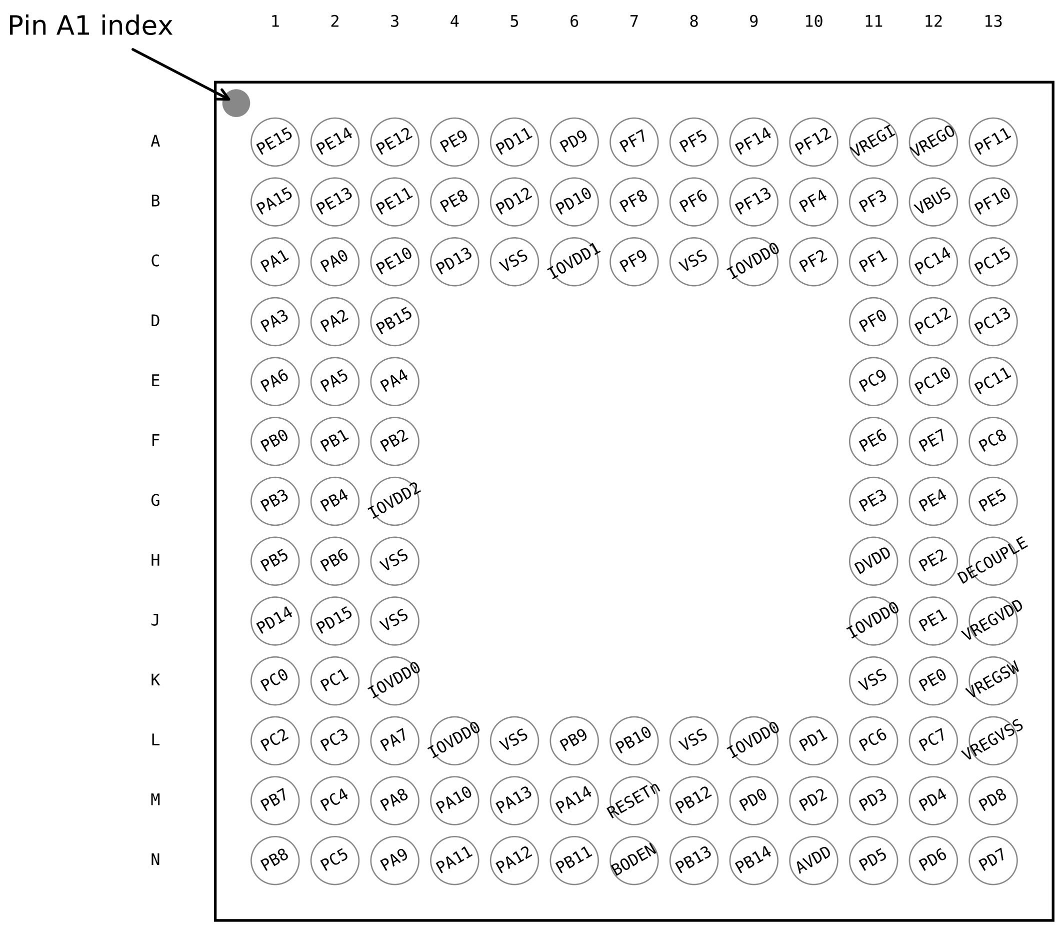

Figure 5.3. EFM32GG11B8xx in BGA120 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see 5.20 GPIO Functionality Table or 5.21 Alternate Functionality Overview.

Table 5.3. EFM32GG11B8xx in BGA120 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PE15	A1	GPIO	PE14	A2	GPIO
PE12	A3	GPIO	PE9	A4	GPIO
PD11	A5	GPIO	PD9	A6	GPIO
PF7	A7	GPIO	PF5	A8	GPIO
PF14	A9	GPIO (5V)	PF12	A10	GPIO
VREGI	A11	Input to 5 V regulator.	VREGO	A12	Decoupling for 5 V regulator and regulator output. Power for USB PHY in USB-enabled OPNs

5.4 EFM32GG11B5xx in BGA120 Device Pinout

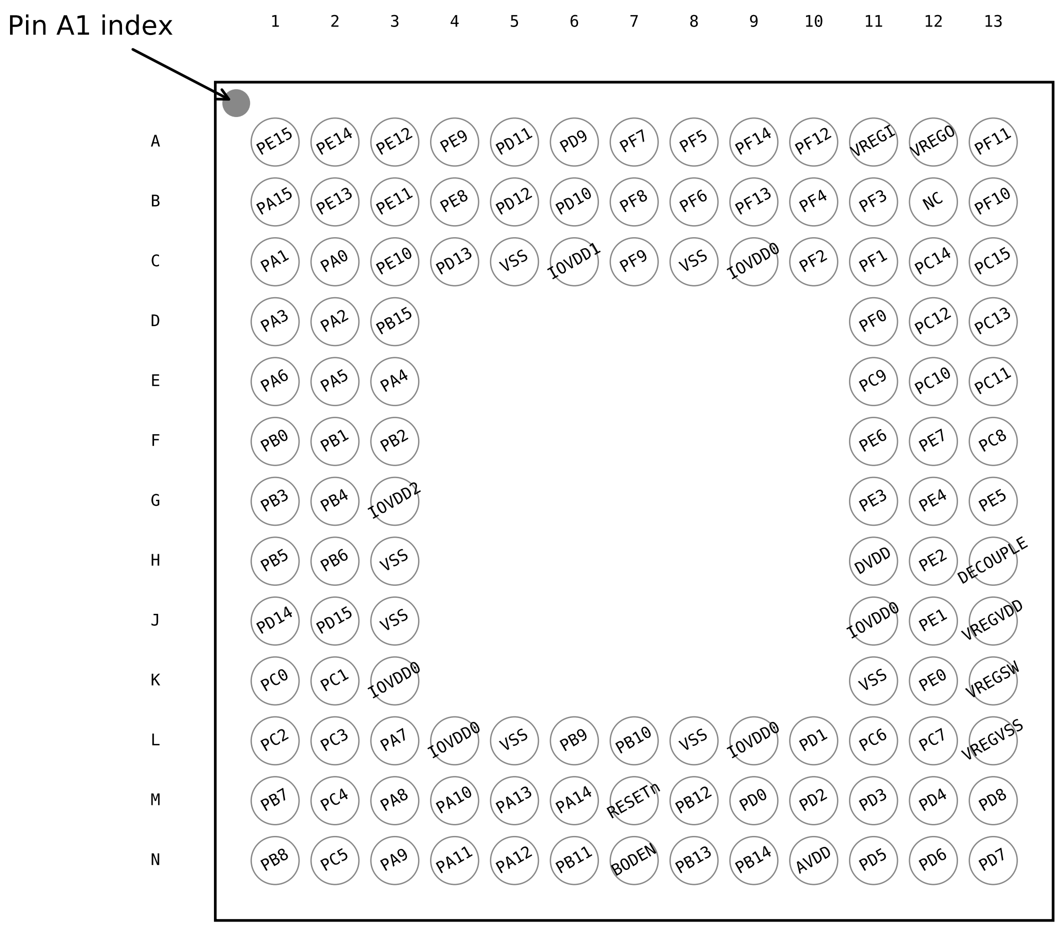

Figure 5.4. EFM32GG11B5xx in BGA120 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see 5.20 GPIO Functionality Table or 5.21 Alternate Functionality Overview.

Table 5.4. EFM32GG11B5xx in BGA120 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PE15	A1	GPIO	PE14	A2	GPIO
PE12	A3	GPIO	PE9	A4	GPIO
PD11	A5	GPIO	PD9	A6	GPIO
PF7	A7	GPIO	PF5	A8	GPIO
PF14	A9	GPIO (5V)	PF12	A10	GPIO
VREGI	A11	Input to 5 V regulator.	VREGO	A12	Decoupling for 5 V regulator and regulator output. Power for USB PHY in USB-enabled OPNs

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PC1	J1	GPIO (5V)	PC3	J2	GPIO (5V)
PD15	J3	GPIO (5V)	PA12	J4	GPIO (5V)
PA9	J5	GPIO	PA10	J6	GPIO
PB9	J7	GPIO (5V)	PB10	J8	GPIO (5V)
PD2	J9	GPIO (5V)	PD3	J10	GPIO
PD4	J11	GPIO	PB7	K1	GPIO
PC4	K2	GPIO	PA13	K3	GPIO (5V)
PA11	K5	GPIO	RESETn	K6	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.
AVDD	K8 K9 L10	Analog power supply.	PD1	K11	GPIO
PB8	L1	GPIO	PC5	L2	GPIO
PA14	L3	GPIO	PB11	L5	GPIO
PB12	L6	GPIO	PB13	L8	GPIO
PB14	L9	GPIO	PD0	L11	GPIO (5V)

Note:

1. GPIO with 5V tolerance are indicated by (5V).
2. The pins PD13, PD14, and PD15 will not be 5V tolerant on all future devices. In order to preserve upgrade options with full hardware compatibility, do not use these pins with 5V domains.

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PF2	78	GPIO	NC	79	No Connect.
PF12	80	GPIO	PF5	81	GPIO
PF6	84	GPIO	PF7	85	GPIO
PF8	86	GPIO	PF9	87	GPIO
PD9	88	GPIO	PD10	89	GPIO
PD11	90	GPIO	PD12	91	GPIO
PE8	92	GPIO	PE9	93	GPIO
PE10	94	GPIO	PE11	95	GPIO
PE12	96	GPIO	PE13	97	GPIO
PE14	98	GPIO	PE15	99	GPIO
PA15	100	GPIO			

Note:

1. GPIO with 5V tolerance are indicated by (5V).

5.20 GPIO Functionality Table

A wide selection of alternate functionality is available for multiplexing to various pins. The following table shows the name of each GPIO pin, followed by the functionality available on that pin. Refer to 5.21 Alternate Functionality Overview for a list of GPIO locations available for each function.

Table 5.20. GPIO Functionality Table

GPIO Name	Pin Alternate Functionality / Description				
	Analog	EBI	Timers	Communication	Other
PA15	BUSAY BUSBX LCD_SEG12	EBI_AD08 #0	TIM3_CC2 #0	ETH_MIIRXCLK #0 ETH_MDIO #3 US2_CLK #3	PRS_CH15 #0
PE15	BUSCY BUSDX LCD_SEG11	EBI_AD07 #0	TIM2_CDTI2 #2 TIM3_CC1 #0	ETH_RMIITXD0 #0 ETH_MIIRXD3 #0 SDIO_CMD #1 US0_RTS #0 QSPI0_DQS #1 LEU0_RX #2	PRS_CH14 #2 ETM_TD3 #4
PE14	BUSDY BUSCX LCD_SEG10	EBI_AD06 #0	TIM2_CDTI1 #2 TIM3_CC0 #0	ETH_RMIITXD1 #0 ETH_MIIRXD2 #0 SDIO_CLK #1 US0_CTS #0 QSPI0_SCLK #1 LEU0_TX #2	PRS_CH13 #2 ETM_TD2 #4
PE13	BUSCY BUSDX LCD_SEG9	EBI_AD05 #0	TIM1_CC3 #1 TIM2_CC2 #3 LE-TIM0_OUT1 #4	SDIO_CLK #0 ETH_MIIRXD1 #0 US0_TX #3 US0_CS #0 U1_RX #4 I2C0_SCL #6	LES_ALTEX7 PRS_CH2 #3 ACMP0_O #0 ETM_TD1 #4 GPIO_EM4WU5
PE12	BUSDY BUSCX LCD_SEG8	EBI_AD04 #0	TIM1_CC2 #1 TIM2_CC1 #3 WTIM0_CDTI2 #0 LETIM0_OUT0 #4	SDIO_CMD #0 ETH_MIIRXD0 #0 US0_RX #3 US0_CLK #0 U1_TX #4 I2C0_SDA #6	CMU_CLK1 #2 CMU_CLKI0 #6 LES_ALTEX6 PRS_CH1 #3 ETM_TD0 #4
PE11	BUSCY BUSDX LCD_SEG7	EBI_AD03 #0 EBI_CS3 #4	TIM1_CC1 #1 TIM4_CC2 #7 WTIM0_CDTI1 #0	SDIO_DAT0 #0 QSPI0_DQ7 #0 ETH_MIIRXDV #0 US0_RX #0	LES_ALTEX5 PRS_CH3 #2 ETM_TCLK #4
PE10	BUSDY BUSCX LCD_SEG6	EBI_AD02 #0 EBI_CS2 #4	TIM1_CC0 #1 TIM4_CC1 #7 WTIM0_CDTI0 #0	SDIO_DAT1 #0 QSPI0_DQ6 #0 ETH_MIIRXER #0 US0_TX #0	PRS_CH2 #2 GPIO_EM4WU9
PE9	BUSCY BUSDX LCD_SEG5	EBI_AD01 #0 EBI_CS1 #4	TIM4_CC0 #7 PCNT2_S1IN #1	SDIO_DAT2 #0 QSPI0_DQ5 #0 US5_RX #0	PRS_CH8 #2
PE8	BUSDY BUSCX LCD_SEG4	EBI_AD00 #0 EBI_CS0 #4	TIM2_CDTI0 #2 TIM4_CC2 #6 PCNT2_S0IN #1	SDIO_DAT3 #0 QSPI0_DQ4 #0 US5_TX #0 I2C2_SDA #0	PRS_CH3 #1
PI9		EBI_A14 #2	TIM1_CC3 #7 TIM4_CC1 #3	US4_CS #3	
PI6		EBI_A11 #2	TIM1_CC0 #7 TIM4_CC1 #2 WTIM3_CC0 #5	US4_TX #3	

GPIO Name	Pin Alternate Functionality / Description				
	Analog	EBI	Timers	Communication	Other
PG3	BUSACMP2Y BUSACMP2X	EBI_AD03 #2	TIM6_CDTI0 #0 WTIM0_CC1 #2 LETIM1_OUT1 #7	ETH_MIITXD1 #1 US3_CS #4 QSPI0_DQ2 #2	
PI5		EBI_A07 #2	WTIM3_CC2 #4	US4_RTS #2 I2C2_SCL #7	ACMP3_O #5
PI4		EBI_A06 #2	WTIM3_CC1 #4	US4_CTS #2 I2C2_SDA #7	ACMP3_O #4
PI3		EBI_A05 #2	WTIM3_CC0 #4	US4_CS #2 I2C1_SCL #7	
PA5	BUSAY BUSBX LCD_SEG18	EBI_AD14 #0	TIM0_CDTI2 #0 TIM3_CC2 #5 PCNT1_S0IN #0	ETH_RMIIRXER #0 ETH_MIITXEN #0 SDIO_DAT5 #1 US3_RTS #0 U0_CTS #2 QSPI0_DQ3 #1 LEU1_TX #1	LES_ALTEX4 PRS_CH17 #0 ACMP1_O #7 ETM_TD3 #3
PG6	BUSACMP2Y BUSACMP2X	EBI_AD06 #2	TIM2_CC1 #7 TIM6_CC0 #1	ETH_MIITXER #1 US3_TX #3 QSPI0_DQ5 #2	
PG5	BUSACMP2Y BUSACMP2X	EBI_AD05 #2	TIM6_CDTI2 #0 TIM2_CC0 #7	ETH_MIITXEN #1 US3_RTS #4 QSPI0_DQ4 #2	
PI2		EBI_A04 #2	TIM5_CC2 #3 WTIM1_CC3 #5 PCNT2_S0IN #5	US4_CLK #2 I2C1_SDA #7	ACMP2_O #5
PI1		EBI_A03 #2	TIM5_CC1 #3 WTIM1_CC2 #5 PCNT2_S1IN #5	US4_RX #2	ACMP2_O #4
PI0		EBI_A02 #2	TIM5_CC0 #3 WTIM1_CC1 #5 PCNT2_S0IN #6	US4_TX #2	ACMP2_O #3
PA6	BUSBY BUSAX LCD_SEG19	EBI_AD15 #0	TIM3_CC0 #6 WTIM0_CC0 #1 LETIM1_OUT1 #0 PCNT1_S1IN #0	ETH_MIITXER #0 ETH_MDC #3 SDIO_CD #2 US5_TX #1 U0_RTS #2 LEU1_RX #1	PRS_CH6 #0 ACMP0_O #4 ETM_TCLK #3 GPIO_EM4WU1
PG8		EBI_AD08 #2	TIM2_CC0 #6 TIM6_CC2 #1 WTIM0_CC0 #3	ETH_MIIRXD3 #1 CAN0_RX #4 US3_CLK #3 QSPI0_DQ7 #2	
PG7	BUSACMP2Y BUSACMP2X	EBI_AD07 #2	TIM2_CC2 #7 TIM6_CC1 #1	ETH_MIIRXCLK #1 US3_RX #3 QSPI0_DQ6 #2	
PE5	BUSCY BUSDX LCD_COM1	EBI_A12 #0 EBI_A17 #1 EBI_A23 #3	TIM3_CC0 #3 TIM3_CC2 #2 TIM5_CC1 #0 TIM6_CDTI1 #2 WTIM0_CC1 #0 WTIM1_CC2 #4	US0_CLK #1 US1_CLK #6 US3_CTS #1 U1_RTS #3 I2C0_SCL #7	PRS_CH17 #2

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
LCD_SEG7	0: PE11		LCD segment line 7.
LCD_SEG8	0: PE12		LCD segment line 8.
LCD_SEG9	0: PE13		LCD segment line 9.
LCD_SEG10	0: PE14		LCD segment line 10.
LCD_SEG11	0: PE15		LCD segment line 11.
LCD_SEG12	0: PA15		LCD segment line 12.
LCD_SEG13	0: PA0		LCD segment line 13.
LCD_SEG14	0: PA1		LCD segment line 14.
LCD_SEG15	0: PA2		LCD segment line 15.
LCD_SEG16	0: PA3		LCD segment line 16.
LCD_SEG17	0: PA4		LCD segment line 17.
LCD_SEG18	0: PA5		LCD segment line 18.
LCD_SEG19	0: PA6		LCD segment line 19.